

REMARKS

Claims 1-22 and 65-69 are presented for consideration. Claims 23-64 are cancelled. Claims 2-22 are currently amended. Claims 65-69 are new.

The Claims are amended to more clearly recite claim limitations.

Claims 1-22 stand rejected under 35 U.S.C. §102(b) as being anticipated by EP 0630044 to Okumura et al.

Applicants respectfully request acknowledgement of the Preliminary Amendment filed June 27, 2002, and of the Request For Approval To Make Drawing Changes filed June 27, 2002.

In a previous Office Action response, the Examiner appears to assert that electroless plating of a surface submerged in a solution is equivalent to solidifying said solution. Since no reference was provided in support of this assertion, Applicants assume that the Examiner is making official notice of this equivalence. Applicants therefore respectfully request that a reference in support of the equivalence of electroless plating to solidification of a liquid be provided.

Applicants respectfully request favorable reconsideration of the present application.

Entry of this Response After Final Rejection, as an earnest attempt to advance prosecution and reduce the number of issues, is respectfully requested. Should the Examiner believe that issues remain outstanding, she is respectfully requested to contact applicants' undersigned attorney in an effort to resolve such issues and advance the case to issue.

Respectfully submitted,

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